

PATENT ASSIGNMENT

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| EFFECTIVE DATE: | 08/21/2007 |

CONVEYING PARTY DATA

| Name | Execution Date |
|-----------------|----------------|
| Swee Kwang Chua | 08/21/2007 |

RECEIVING PARTY DATA

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|-----------------|------------------------------------|
| Name: | Micron Technology, Inc. |
| Street Address: | 8000 South Federal Way, P.O. Box 6 |
| City: | Boise |
| State/Country: | IDAHO |
| Postal Code: | 83716-9632 |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 11861143 |

CORRESPONDENCE DATA

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| ATTORNEY DOCKET NUMBER: | 108298915US |
| NAME OF SUBMITTER: | John M. Weckin |

Total Attachments: 3
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OP \$40.00 11861143


ASSIGNMENT

THIS ASSIGNMENT is by Chua Swee Kwang (the "Assignor"), residing at Block 207D, Compassvale Lane, #07-56, Republic of Singapore 547207. The Assignor has invented one or more certain inventions (the "Invention(s)") described in a United States Patent Application entitled "THIN SEMICONDUCTOR DIE PACKAGES AND ASSOCIATED SYSTEMS AND METHODS" (the "Application") and executed concurrently herewith.


Micron Technology, Inc., a corporation of the State of Delaware having a place of business at 8000 South Federal Way, P.O. Box 6, Boise, Idaho 83716-9632 ("Assignee"), desires to acquire the entire right, title and interest in and to the Invention(s) and the Application, and in and to any patents (collectively, "Patents") that may be granted for the Invention(s) in the United States or in any foreign countries.

For valuable consideration, the receipt and sufficiency of which I acknowledge, Assignor hereby sells, assigns, and transfers to Assignee, its successors, legal representatives and assigns, the entire right, title and interest in and to: the Invention(s), the Application, and any Patents; any divisions, continuations, and continuations-in-part of the Application and any other application claiming priority rights from the Application; any reissues, reexaminations, or extensions of any and all Patents; the right to file foreign applications directly in the name of Assignee; and the right to claim priority rights deriving from the Application (collectively, the "Rights"). Assignor warrants that he or she is the sole owner of the Rights, and that the Rights are unencumbered. Assignor also agrees to not sign any writing or do any act conflicting with this assignment, and, without further compensation, sign all documents and do such additional acts as Assignee deems necessary or desirable to: perfect Assignee's enjoyment of the Rights; prepare and prosecute the Application or any other applications for Patents; conduct proceedings regarding the Rights, including any litigation or interference proceedings; or perfect or defend title to the Rights. Assignor requests the Commissioner of Patents to issue any Patent of the United States that may be issued on the Invention(s) to Assignee.

Date: 21 August 2007


Chua Swee Kwang

WITNESS TO SIGNATURE BY CHUA SWEE KWANG


Signature
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21-Aug-2007
Date

Date: 8/31/07



Russell D. Slifer
Chief Patent Counsel
MICRON TECHNOLOGY, INC.
